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9-25-00
Robert

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Po-Yao Lin et al.

Serial No.: 09/379,599

Filed: August 24, 1999

For: Integrated Circuit Package with
Multiple Heat Dissipation Paths

Art Unit:

Examiner: Chervinnsky

Atty Docket: 0694/00063

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PRELIMINARY AMENDMENT

VIA FAX NO. 703-305-3431

Commissioner for Patents
Washington, D.C. 20231

Sir:

Prior to initial examination, please amend the above-captioned case as follows.

IN THE CLAIMS

Please cancel claims 2, 5, 6 and 7 without prejudice to their reentry at some later date.

Please amend the claims as follows.

1. (Amended) An integrated circuit package comprising:
a printed circuit board;
a die attached to the printed circuit board; and
a heat spreader covering the die, the heat spreader contacting with backside of the die and being mounted to the printed circuit board;

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